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IN THE CLAIMS:

1 Claims- 1-17 (canceled)

2 Claim 18 (currently amended). A substrate for receiving a die-down die and pro-
3 viding electrical contacts re-orientated into a die-up orientation, the die-down die defin-
4 ing electrical contacts, the substrate comprising:

5 a plurality of electrically conductive traces defining first contacts, the first con-
6 tacts arranged in an orientation to accept connector wires for making electrical connec-
7 tions from the electrical contacts of a single die-down die, if one was mounted,

8 the plurality of electrically conductive traces running under and from one side to
9 the opposite side of a single die down die, if one was mounted, and

10 wherein the electrical traces define second contacts located on the opposite side
11 relative to the first contacts, the second contacts arranged in a die up orientation, arranged
12 to correspond to the die-up orientation of a single die-up die,

13 wherein the substrate can be placed into a package designed to accept a single die-
14 up die, and wherein electrical connections may be made to the substrate's second contacts
15 as if it were a single die-up die.

1 Claim 19 (previously presented). The substrate of claim 18 further comprising:

2 a single die-down die mounted to the substrate,

3 connector wires joining the electrical contacts of the die-down die to the
4 first contacts on the conductive traces,

5 and

6 electrically conductive wires joining the second contacts on the conductive
7 traces to contacts on a lead frame.

1 Claim 20. (canceled).

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1 Claim 21. (previously presented). The substrate of claim 19 further comprising
2 non-conductive means for attaching the substrate to the single die-down die.

1 Claim 22. (previously presented). The substrate of claim 18 wherein the substrate
2 comprises a material selected from the groups consisting of ceramic and organic.

1 Claim 23. (previously presented). The substrate of claim 19 wherein the single
2 die-down die is an integrated circuit.

1 Claim 24. (canceled).

1 Claims 25-31 (withdrawn).

1 Claim 32 (deleted).

1 Claim 33. (deleted).

1 Claim 34. (previously presented). The die attach package of claim 45 further
2 comprising non-conductive means for attaching the substrate to the single die-down die.

1 Claim 35. (previously presented). The die attach package of claim 45 wherein the
2 substrate comprises a material selected from the groups consisting of ceramic and or-
3 ganic.

1 Claim 36. (previously presented). The die attach package of claim 45 wherein the
2 single die-down die is an integrated circuit.

1 Claim 37. (previously presented). The die attach package of claim 45 wherein the
2 single die-down die includes components attached to the die-down die.

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Claim 38-44. (Withdrawn).

1 Claim 45 (previously presented). A die attach package for receiving a single die
2 with contacts arranged in a die-up orientation, the die attach package comprising:
3 a substrate as defined in claim 18,
4 a lead frame with contacts,
5 connector wires joining the second contacts on the traces to the lead frame
6 contacts.